



ASMNUT.001A

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Uzoh et al.
Appl. No. : 10/769,605
Filed : January 30, 2004
For : METHOD OF
ELECTROPLATING COPPER
LAYERS WITH FLAT
TOPOGRAPHY
Examiner : Nira S. Birenbaum
Group Art Unit : 1742

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

March 9, 2006

(Date)

Adeel S. Akhtar, Reg. No. 41,394

RESPONSE TO OFFICE ACTION

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed on October 17, 2005, please amend the above-captioned application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

500.00 QP

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